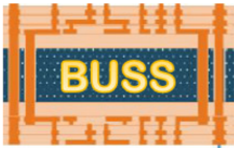
BUILD-UP SUBSTRATE SYMPOSIUM 2024 – Advance Program **Register: www.ieee-buss.org**

May 2nd	Schedule	Speakers	Affiliation	Talk Title
Opening	8:30am	Habib Hichri	Ajinomoto	Opening and BUSS program
Keynote I	8:45am	Daniel Burger	NAPMP, Associate Director	Keynote:NAPMP Plans & Advanced Substrate Onshoring
Keynote II	9:30am	D.C. Hu	SiPlus, Founder	2.XD Integrated Substrate Solutions for High Performance Computing
	10:15am Tea Break			
Substrate Manufacturing & Onshoring (Chair: Rozalia Beica)	11:00am	Sundar Kamath	Sanmina	
	11:20am	Meredeth LaBeau	Calumet, CTO	Onshoring Organic Substrates (High-Density Build-Ups):A tale of Domestic Manufacturing & Title 3 Investments
	11:40am	Sung Jin Kim (CTO)	Absolics, CTO	Packaging Substrate Solutions for Advanced Packaging Requirements
	12:00pm			
	12:20pm Lunch from Dish Dash			
Materials Advances for Substrates (Chair: Annette Teng)	1:30pm	Yishio Nishimura	Ajinomoto	Advanced Insulating Material for Next Generation Packaging
	1:50pm	Yuta Ogawa	TaivoInk	Taiyo's Photo-Dielectric for High Density Substrate Applications
	2:10pm	Fukui Masato	Resonac	Substrate Materials for Advanced Packaging
	2:30pm	Hikaru Mizuno	JSR Micro	Novel Low Loss Materials for Advanced IC Packaging
Emerging Substrate Technologies (Chair: Steven Verhaverbeke)	2:50pm	Steven Verhaverbeke	AMAT	Wafer Level Substrates – An Emerging New Technology
	3:10pm	Farhang Yazdani	BroadPak	Advanced X64 UCIe Interface Implementatio on a Substrate
	3:30pm	Ken Yang, Vineeth Harish	UCLA	Chiplet Integration on Organic Buildup with Silicon Interconnect Fabric
	3:50pm Tea Break			
"Substrate Needs: User Perspective" Panel session moderated by Jan Vardaman	4:30pm	Sai Boyapati	AMD, Sr. Dir. Adv. Pkg.	Substrate Needs: The User Perspective
		Diane Peng	Marvell	
		Omar Bchir	Qualcomm	
		Susan Bagen	Raytheon, Microelectronics Cslt.	
		Jon Woodyard	Microsoft, Principal Engineer	
	5:30pm	*Barbecue Dinner catered by Armadillo Willy's*		

May 3rd Friday	Schedule	Speakers	Affiliation	Talk Title
Keynote I	9:00am	Venky Sundaram	3dsystemscaling, Founder	USA Landscape for Substrate Manufacturing
Keynote II	9:35am	Rahul Iyer	KCK Group	Venture Funding for startups
	10:10am	*Tea break*		
Panel Equipment for Substrates (Chair Kuldip Johal)	11:00am	Kyle Baker	MKS Instruments	QCW CO2 laser drilling for FCBGA applications.
	11:20am	Takuma Yoshikawa	Nikko Materials	The Latest Vacuum Lamination Challenges and Technology
	11:40am	Frank Bruening	MSD-Atotech	Systems solutions for Advanced IC substrate manufacturing
	12:00pm	*LUNCH*		
Panel Equipment and Technologies for Substrates (Chair: Kuldip Johal)	1:00pm	Rozalia Beica	LQDX	The Future of AI and HPC Substrates: A Breakthrough Interconnect Technology
	1:20pm	Harish Penmethsa	Applied Materials	
	1:40pm	Keith Best	Onto Innovation	Challenges for Organic & Glass Core Substrates as Advanced Packaging RDL Approaches < 2 μm L/S
	2:00pm	Gustavo Ramos	Green Source Engineering	Manufacturing with Zero Liquid Discharge (ZLD)
	2:20pm	Saminda Dharmarathna	MacDermid Alpha	Advanced Electroplating Processes for IC Substrates – Redistribution Layer and Embedded Trenches
	2:40pm	Purnima Narayanan	YES	Advanced packaging metallization-Substrate interaction with catalyst & electroless deposition of Cu
	3:00pm	*Tea break*		
Inspection and Testing (Chair: Farhang)	3:20pm	Robert Bishop	Beltonics	Advanced Metrology for High Density Substrates
	3:40pm		Tessolve	
	4:00pm	Orit Hava Armon Hershkovich	KLA Corporation	Inspection challenges in ICS & Advanced panel packaging markets
"Onshoring & Startups" Panel session moderated by Venky Sundaram	4:20pm	Simon McElrea	LQDX	Onshoring and Startups: Design, Equipment, Material & Products
		Siddharth Ravichandran	Chipletz	
			Calumet	
			Nubis Communication	
			Green Source Engineering	
Closing remarks	5:20pm			



1st BUILD-UP SUBSTRATE SYMPOSIUM

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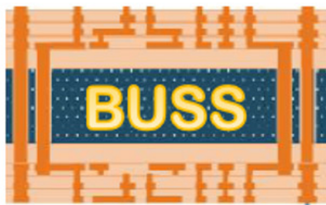

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